



Transcend's DDR4 DRAM modules operate at a nominal voltage of just 1.2V, offering higher energy efficiency and exceptional clock speeds to cater to the demands of the embedded industry. The modules are available in multiple form factors and technologies, such as ECC and wide-temperature support. All components are of the highest quality, having been sourced directly from the world's first-tier supplier of DRAM chips and stringently tested for unparalleled compatibility, reliability, and performance.

#### **Features**

- JEDEC standard 1.2V ± 0.06V power supply
- High energy efficiency
- 8 bit pre-fetch
- Burst Length: 4, 8
- 16 Banks (4 Bank Groups)
- · Support DBI mode
- · Support Command/Address parity detection
- Support Data Cyclic Redundancy Check (CRC) for improved data reliability
- On-die termination with ODT pin
- Serial presence detect with EEPROM
- 100% tested for stability, compatibility and performance

### **Advanced Technologies**







Anti-Sulfur Technology

orner Bond & Underfill

Conformal Coating



Wide Temperature



30 μ Gold Finger



# **DDR4 Unbuffered DIMMs**



M. I.I.T.	DDR	R4
Module Type	Long-DIMM	SO-DIMM
Product Image	TSJOLISEANO PLANE DE PROMINE DE LE CONTROLISE DE LE CONTR	TEODISCOVE
Standard	JEDE	EC
Frequency	3200/2666/2	2400/2133 MHz
Capacity	2GB~3	2GB
Voltage	1.2\	V
Pin Count	Long-DIMM: 288 pin	SO-DIMM: 260 pin
PCB Height	Standard: 1.23 inches Very Low Profile: 0.74 inches	1.18 inches
Operating Temperature	Standard Tempera Wide Temperatur	

## **Ordering Information**

#### DDR4-3200 Long-DIMM

Capacity	Component Composition	Rank x Org.	Standard (1.2V)	Wide Temp. (-40°C~ 85°C)	Very Low Profile (VLP)
8GB	(1Gx8)x8	1Rx8	TS1GLH64V2B	-	-
8GB	(1Gx8)x8	1Rx8	TS1GLH64V2B2	-	-
8GB	(1Gx8)x8	1Rx8	TS1GLH64V2B-G	-	-
16GB	(1Gx8)x16	2Rx8	TS2GLH64V2B	-	-
16GB	(1Gx8)x16	2Rx8	TS2GLH64V2B2	-	-
16GB	(1Gx8)x16	2Rx8	TS2GLH64V2B-G	-	-
16GB	(2Gx8)x8	1Rx8	TS2GLH64V2E	-	-
32GB	(2Gx8)x16	2Rx8	TS4GLH64V2E	-	-
32GB	(2Gx8)x16	2Rx8	TS4GLH64V2E-G	-	-

#### **DDR4-3200 SO-DIMM**

Capacity	Component Composition	Rank x Org.	Standard (1.2V)	Wide Temp. (-40°C∼ 85°C)	Very Low Profile (VLP)
8GB	(1Gx8)x8	1Rx8	TS1GSH64V2B2	-	-
8GB	(1Gx8)x8	1Rx8	TS1GSH64V2B-G	-	-
16GB	(1Gx8)x16	2Rx8	TS2GGSH64V2B	TS2GGSH64V2B-I	-
16GB	(1Gx8)x16	2Rx8	TS2GSH64V2B2	-	-
16GB	(1Gx8)x16	2Rx8	TS2GSH64V2B-G	-	-
16GB	(2Gx8)x8	1Rx8	TS2GSH64V2E	-	-
32GB	(1Gx8)x16	2Rx8	TS4GSH64V2E	-	-
32GB	(1Gx8)x16	2Rx8	TS4GSH64V2E-G	-	-



#### DDR4-2666 Long-DIMM

Capacity	Component Composition	Rank x Org.	Standard (1.2V)	Wide Temp. ( <del>-</del> 40°C~ 85°C)	Very Low Profile (VLP)
2GB	(256Mx16)x4	1Rx16	TS256MLH64V6X		TS256MLH64V6XL
4GB	(512Mx16)x4	1Rx16	TS512MLH64V6D	- 1	
4GB	(512Mx8)x8	1Rx8	TS512MLH64V6H	<b>₹</b>	TS512MLH64V6HL
8GB	(1Gx8)x8	1Rx8	TS1GLH64V6B	TS1GLH64V6B-I	TS1GLH64V6BL
8GB	(1Gx8)x8	1Rx8	TS1GLH64V6B2		, · · · ·
16GB	(1Gx8)x16	2Rx8	TS2GLH64V6B	TS2GLH64V6B-I	TS2GLH64V6BL
16GB	(1Gx8)x16	2Rx8	TS2GLH64V6B2	-	-
32GB	(2Gx8)x16	2Rx8	TS4GLH64V6E	TS4GLH64V6E-I	TS4GLH64V6EL
32GB	(2Gx8)x16	2Rx8	TS4GLH64V6E2		2,10

#### **DDR4-2666 SO-DIMM**

Capacity	Component Composition	Rank x Org.	Standard (1.2V)	Wide Temp. (-40°C∼ 85°C)
2GB	(256Mx16)x4	1Rx16	TS256MSH64V6X	- 6
4GB	(512Mx16)x4	1Rx16	TS512MSH64V6D	^
4GB	(512Mx8)x8	1Rx8	TS512MSH64V6H	TS512MSH64V6H-I
8GB	(512Mx8)x16	2Rx8	TS1GSH64V6H	
8GB	(1Gx8)x8	1Rx8	TS1GSH64V6B	TS1GSH64V6B-I
8GB	(1Gx8)x8	1Rx8	TS1GSH64V6B2	
16GB	(1Gx8)x16	2Rx8	TS2GSH64V6B	TS2GSH64V6B-I
16GB	(1Gx8)x16	2Rx8	TS2GSH64V6B2	-
32GB	(2Gx8)x16	2Rx8	TS4GSH64V6E	TS4GSH64V6E-I
32GB	(2Gx8)x16	2Rx8	TS4GSH64V6E2	-

#### DDR4-2400 Long-DIMM

Capacity	Component Composition	Rank x Org.	Standard (1.2V)	Wide Temp. (-40°C~ 85°C)	Very Low Profile (VLP)
4GB	(512Mx8)x8	1Rx8	TS512MLH64V4H	-	TS512MLH64V4HL
8GB	(512Mx8)x16	2Rx8	TS1GLH64V4H	-	-
8GB	(1Gx8)x8	1Rx8	TS1GLH64V4B	TS1GLH64V4B-I	-
16GB	(1Gx8)x16	2Rx8	TS2GLH64V4B	-	TS2GLH64V4BL

#### DDR4-2400 SO-DIMM

Capacity	Component Composition	Rank x Org.	Standard (1.2V)	Wide Temp. (-40°C∼ 85°C)	
2GB	(256Mx16)x4	1Rx16	TS256MSH64V4X	-	
4GB	(512Mx16)x4	1Rx16	TS512MSH64V4D	-	
4GB	(512Mx8)x8	1Rx8	TS512MSH64V4H	TS512MSH64V4H-I	
8GB	(512Mx8)x16	2Rx8	TS1GSH64V4H	-	
8GB	(1Gx8)x8	1Rx8	TS1GSH64V4B	TS1GSH64V4B-I	
16GB	(1Gx8)x16	2Rx8	TS2GSH64V4B	TS2GSH64V4B-I	





Capacity	Component Composition	Rank x Org.	Standard (1.2V)	Wide Temp. (-40°C~ 85°C) (VLP)	
4GB	(512Mx8)x8	1Rx8	TS512MLH64V1H		
8GB	(512Mx8)x16	2Rx8	TS1GLH64V1H	- TS1GLH64V1HL	
16GB	(1Gx8)x16	2Rx8	TS2GLH64V1B	-	

#### **DDR4-2133 SO-DIMM**

Capacity	Component Composition	Rank x Org.	Standard (1.2V)	Wide Temp. (-40°C∼ 85°C)
4GB	(512Mx8)x8	1Rx8	TS512MSH64V1H	TS512MSH64V1H-I
8GB	(512Mx8)x16	2Rx8	TS1GSH64V1H	TS1GSH64V1H-I
16GB	(1Gx8)x16	2Rx8	TS2GSH64V1B	TS2GSH64V1B-I
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## **DDR4 ECC DIMMs**



	DDR4				
Module Type	υ .	UK4			
Woddie Type	ECC Long-DIMM	ECC SO-DIMM			
Product Image	TESOLITYZMA Maria maria coloris plant a po Maria de la coloris de la colorista de la coloris de la colorista de la coloris de la colorista de la coloris de la colorista della colorista de la colorista de la colorista de la colorista della col	TS/GSFT/2V-00 CO-STAND TO THE PARTY OF THE P			
Standard	JE	DEC			
Frequency	3200/2666/2400/2133 MHz				
Capacity	4GB	~32GB			
Voltage	1	.2V			
Pin Count	ECC Long-DIMM: 288 pin	ECC SO-DIMM: 260 pin			
PCB Height	Standard: 1.23 inches Very Low Profile: 0.74 inches	1.18 inches			
PCB Gold Finger Thickness	3	0μ"			
Anti-Sulfuration	De	efault			
Operating Temperature		erature: 0°C~ 85°C ture: -40°C~ 85°C			

## **Ordering Information**

#### DDR4-3200 ECC Long-DIMM

Capacity	Component Composition	Rank x Org.	Standard (1.2V)	Wide Temp. (-40°C~ 85°C)	Very Low Profile (VLP)
8GB	(1Gx8)x9	1Rx8	TS1GLH72V2B	-	-
16GB	(1Gx8)x18	2Rx8	TS2GLH72V2B	TS2GLH72V2B-I	-
32GB	(2Gx8)x18	2Rx8	TS4GLH72V2E	-	-

#### **DDR4-3200 ECC SO-DIMM**

Capacity	Component Composition	Rank x Org.	Standard (1.2V)	Wide Temp. (-40°C~ 85°C)	Very Low Profile (VLP)
8GB	(1Gx8)x9	1Rx8	TS1GSH72V2B	-	-
16GB	(1Gx8)x18	2Rx8	TS2GSH72V2B	-	-
32GB	(2Gx8)x18	2Rx8	TS4GSH72V2E	-	-

#### DDR4-2666 ECC Long-DIMM

Capacity	Component Composition	Rank x Org.	Standard (1.2V)	Wide Temp. (-40°C~ 85°C)	Very Low Profile (VLP)
4GB	(512Mx8)x9	1Rx8	TS512MLH72V6H	TS512MLH72V6H-I	TS512MLH72V6HL
8GB	(1Gx8)x9	1Rx8	TS1GLH72V6B	TS1GLH72V6B-I	TS1GLH72V6BL
16GB	(1Gx8)x18	2Rx8	TS2GLH72V6B	TS2GLH72V6B-I	TS2GLH72V6BL
32GB	(2Gx8)x18	2Rx8	TS4GLH72V6E	TS4GLH72V6E-I	TS4GLH72V6EL
32GB	(2Gx8)x18	2Rx8	TS4GLH72V6E2	-	-





Capacity	Component Composition	Rank x Org.	Standard (1.2V)	Wide Temp. (-40°C~ 85°C)
4GB	(512Mx8)x9	1Rx8	TS512MSH72V6H	TS512MSH72V6H-I
8GB	(1Gx8)x9	1Rx8	TS1GSH72V6B	TS1GSH72V6B-I
16GB	(1Gx8)x18	2Rx8	TS2GSH72V6B	TS2GSH72V6B-I
32GB	(2Gx8)x18	2Rx8	TS4GSH72V6E	TS4GSH72V6E-I
32GB	(2Gx8)x18	2Rx8	TS4GSH72V6E2	150

#### **DDR4-2400 ECC Long-DIMM**

Capacity	Component Composition	Rank x Org.	Standard (1.2V)	Wide Temp. (-40°C~ 85°C)	Very Low Profile (VLP)
4GB	(512Mx8)x9	1Rx8	TS512MLH72V4H	~	-
8GB	(1Gx8)x9	1Rx8	TS1GLH72V4B	. 0	-
16GB	(1Gx8)x18	2Rx8	TS2GLH72V4B		-
32GB	(2Gx8)x18	2Rx8	TS4GLH72V4E	~(),	-

#### **DDR4-2400 ECC SO-DIMM**

Capacity	Component Composition	Rank x Org.	Standard (1.2V)	Wide Temp. $(-40^{\circ}\text{C} \sim 85^{\circ}\text{C})$	
4GB	(512Mx8)x9	1Rx8	TS512MSH72V4H	-	
8GB	(512Mx8)x18	2Rx8	7.	TS1GSH72V4H-I	
8GB	(1Gx8)x9	1Rx8	TS1GSH72V4B	TS1GSH72V4B-I	
16GB	(1Gx8)x18	2Rx8	TS2GSH72V4B	TS2GSH72V4B-I	

#### DDR4-2133 ECC Long-DIMM

Capacity	Component Composition	Rank x Org.	Standard (1.2V)	Wide Temp. (-40°C~ 85°C)	Very Low Profile (VLP)
4GB	(512Mx8)x9	1Rx8	TS512MLH72V1H	-	-
8GB	(512Mx8)x18	2Rx8	TS1GLH72V1H	-	-
16GB	(1Gx8)x18	2Rx8	TS2GLH72V1B	-	-

#### DDR4-2133 ECC SO-DIMM

Capacity	Component Composition	Rank x Org.	Standard (1.2V)	Wide Temp. (-40°C~ 85°C)	
4GB	(512Mx8)x9	1Rx8	TS512MSH72V1H	-	
8GB	(512Mx8)x18	2Rx8	TS1GSH72V1H	TS1GSH72V1H-I	
16GB	(1Gx8)x18	2Rx8	TS2GSH72V1B	TS2GSH72V1B-I	



# **DDR4 Registered DIMMs**



Madula Typa	DDR4				
Module Type	Registered DIMM				
Product Image	TS CONTYNUE  TO CO				
Standard	JEDEC				
Frequency	3200/2666/2400/2133 MHz				
Capacity	4GB~32GB				
Voltage	1.2V				
Pin Count	R-DIMM: 288 pin				
PCB Height	Standard: 1.23 inches Very Low Profile: 0.74 inches				
PCB Gold Finger Thickness	30μ″				
Anti-Sulfuration	Default				
Operating Temperature	Standard Temperature: 0°C~ 85°C				

## **Ordering Information**

#### **DDR4-3200 Registered DIMM**

Capacity	Component Composition	Rank x Org.	Standard (1.2V)	Very Low Profile (VLP)
8GB	(1Gx8)x9	1Rx8	TS1GHR72V2B	-
16GB	(1Gx8)x18	2Rx8	TS2GHR72V2B	TS2GHR72V2BL
32GB	(2Gx8)x18	2Rx8	TS4GHR72V2E	TS4GHR72V2EL



#### **DDR4-2666 Registered DIMM**

Capacity	Component Composition	Rank x Org.	Standard (1.2V)	Very Low Profile (VLP)
4GB	(512Mx8)x9	1Rx8	TS512MHR72V6H	
8GB	(512Mx8)x18	2Rx8	TS1GHR72V6H	TS1GHR72V6HL
8GB	(1Gx8)x9	1Rx8	TS1GHR72V6B	-
16GB	(1Gx8)x18	2Rx8	TS2GHR72V6B	TS2GHR72V6BL
32GB	(2Gx4)x36	2Rx4	TS4GHR72V6C	-
32GB	(2Gx8)x18	2Rx8	TS4GHR72V6E	TS4GHR72V6EL
32GB	(2Gx8)x18	2Rx8	TS4GHR72V6E2	

#### **DDR4-2400 Registered DIMM**

Capacity	Component Composition	Rank x Org.	Standard (1.2V)	Very Low Profile (VLP)
4GB	(512Mx8)x9	1Rx8	TS512MHR72V4H	-
8GB	(512Mx8)x18	2Rx8	TS1GHR72V4H	TS1GHR72V4HL
8GB	(1Gx8)x9	1Rx8	TS1GHR72V4B	-
16GB	(1Gx8)x18	2Rx8	TS2GHR72V4B	TS2GHR72V4BL
32GB	(2Gx4)x36	2Rx4	TS4GHR72V4C	-

#### **DDR4-2133 Registered DIMM**

Capacity	Component Composition	Rank x Org.	Standard (1.2V)	Very Low Profile (VLP)
4GB	(512Mx8)x9	1Rx8	TS512MHR72V1H	-
8GB	(512Mx8)x18	2Rx8	TS1GHR72V1H	TS1GHR72V1HL
16GB	(1Gx8)x18	2Rx8	TS2GHR72V1B	TS2GHR72V1BL
32GB	(2Gx4)x36	2Rx4	TS4GHR72V1C	-

Product specifications are subject to change without notice. Pictures shown may differ from actual products. Due to the complexity and variety of industrial applications, Transcend cannot guarantee 100% compatibility with all platforms and under all scenarios. For special applications and environments, it is strongly suggested that you contact Transcend beforehand for clarification.



